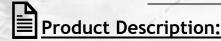


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EPMU





APPLICATION INSTRUCTIONS

DIMAPCHEM-EP (MU) is a two packs, high build, solvent epoxy coating for, steel structures and concrete to provide protection from weathering abrasion and corrosion. It provides a durable coating suitable for application to both vertical Surface Preparation: Steel & Concrete Surfaces: Oil contaminated surfaces should be thoroughly cleaned with a degreaser and sand blasted. Where this is not possible, minimal surface preparation of wire brushing should be done. DIMAPCHEM-EP (MU) can be applied directly to steel & concrete surfaces.

Priming: Normally primer is not required. But after grit blasting / sand blasting, if there is any delay to erection, one coat of DIMAPCHEM-EP (MU) up 60% with DIMAPCHEM-VERLASOL EP is advisable to prevent further flush rust.

Mixing: DIMAPCHEM-EP (MU) is supplied as ready to use in pre-weighed packs of resin and hardener for easy on-site mixing. Pour the hardener into the resin can, mix well using a paddle attached to an electric drill, for 2-3 minutes until a uniform color is obtained.

Health and Safety:

- **Precautions:** Wear gloves and eye protection, ensure good ventilation, and avoid skin and inhalation contact.
- Storage: Store in a cool, dry place, away from sunlight and children.

Technical Details

Property	Typical Value
Appearance	Granular / powder
Specific Gravity	$1.60 - 1.90 \text{ g/cm}^3$
Curing Time	1-2 minutes at 175
	°C
Thermal Conductivity	$0.6-1.0 \text{ W/m}\cdot\text{K}$
Glass Transition Temperature	130 − 180 °C
(Tg)	1
Dielectric Strength	≥18 kV/mm
Volume Resistivity	≥10 ¹⁴ ohm·cm
Flexural Strength	≥100 MPa
Water Absorption (24hr)	< 0.2%
Flame Resistance	UL94 V-0 (with
STEEL HAT COLD STEEL	additives)

Quality & Durability:

- High mechanical strength
- Excellent thermal stability
- Strong electrical insulating properties
- Moisture and chemical resistance
- Good flame retardancy (when formulated accordingly)
- Moldability and fast curing

Uses:

- Encapsulation of electronic components (diodes, transistors, ICs). Potting and sealing of automotive electronic devices
- Electrical insulators and bushings.
- Circuit board protection against moisture, dust, and vibration